

## **FlipChip International Appoints David McComb as Vice President Sales and Marketing**

PHOENIX, Arizona, Sept 24, 2007---FlipChip International, LLC announced today that it has appointed David McComb as Global Vice President Sales and Marketing for its semiconductor wafer scale packaging and bumping business. David McComb will assume responsibilities for sales, marketing and licensing for FCI's activities for its international customers. David McComb's background includes over 30 years in the package development and high volume electronics manufacturing businesses.

David McComb started his career in Mechanical Engineering working at Edinburgh University and The Medical Research Council in Edinburgh, Scotland. A move into manufacturing in the PWB industry led to an opportunity in Sales and Marketing with Park Electrochemical Corp. where David was ultimately responsible for leading the Sales team servicing the European marketplace with High Technology electronic substrates. David joined FCI as the Director of European Business and Sales in September 2005. David received his degree in Mechanical Engineering from Edinburgh University.

Bob Forcier, President and CEO of FlipChip International, stated, "We are very excited to have David McComb assume the additional responsibilities of global sales and marketing. His outstanding contribution since joining our team in Phoenix has accelerated FCI's growth and his enthusiasm for the potential of FCI is unparalleled. As the wafer level packaging market gets revved up for a strong 2008, David will be leading our outstanding sales team. To support Dave's new role, Mr. Dave Clark will move up to European Accounts Manager with additional responsibilities for the co-ordination of FCI developments in 3D packaging. In the US market, Bruce Bowers, Jay Hayes and Jim Graham will continue their excellent work and Janine Schmitz will take on the role as Internal Sales Manager."

David McComb said, "The opportunities available to FCI in the coming months and years are enormous and I am proud to take up this tremendous challenge. With the support of our talented Sales, Engineering and Operations teams, I am confident in the company's growth opportunities which are founded on FCI's excellent IP portfolio, strong innovation / engineering development activities and High Volume Manufacturing progress."

FlipChip International, LLC is privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for the life sciences, semiconductor services and renewable energy markets.

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